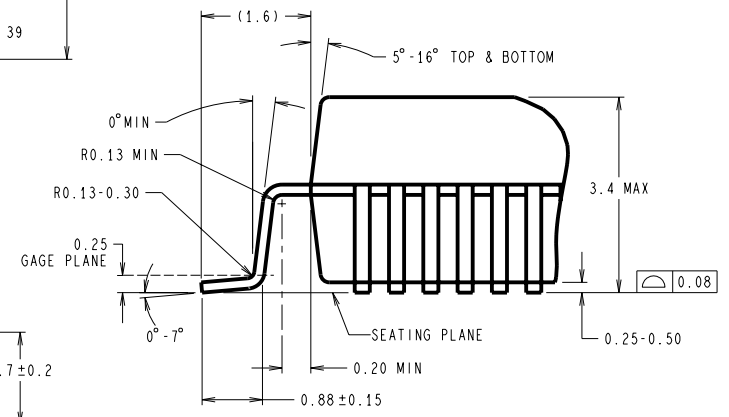


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10349	03/25/94	DEG/HJK
B	DET A: DIM 0.25-0.50 WAS 0.05-0.25	11948	03/06/1998	MS/RW
C	DIM 23.2 ± 0.2 WAS 23.23 ± 0.25; DIM 17.2 ± 0.2 WAS 17.23 ± 0.25; DIM 2.7 ± 0.2 WAS 2.70 ± 0.02; DIM 3.4 MAX WAS 3.15 MAX; DIM 0.2 MIN WAS 0.40 MIN; DIM 0.88 ± 0.15 WAS 0.88 ± 0.10.	12012	06/15/1998	MS/



DETAIL A  
SCALE: 20X

DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:  
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)  
THICKNESS ON COPPER.
  - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
  - REFERENCE ASAT DWG# DG2003, DATED 07/09/93.

<b>APPROVALS</b>		<b>DATE</b>	<b>NATIONAL SEMICONDUCTOR CORPORATION</b>		
DRAWN	<i>D. E. Grady</i>	03/25/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFTG. CHK.			<b>QFP,</b> <b>(S), 14 X 20 X 2.7mm,</b> <b>128 LEAD</b>		
ENGR. CHK.					
APPROVAL					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-VLA128A	C
		DO NOT SCALE DRAWING		SHEET 1 of 1	